

Solid State Detectors

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Semi-Conductor based Detectors

- Materials and their properties
- Energy bands and electronic structure
- Charge transport and conductivity
- Boundaries: the p-n junction
- Charge collection
- Energy and time resolution
- Radiation damage

Signal Generation → Needs transfer of Energy

Any form of elementary excitation can be used to detect the radiation signal

An electrical signal is generated by ionization: Incident radiation quanta transfer sufficient energy to form electron-hole pairs

Other detection mechanisms are:

- Excitation of optical states (scintillators)

- Excitation of lattice vibrations (phonons)

- Breakup of Cooper pairs in superconductors

Typical excitation energies:

 - Ionization in semiconductors: 1 – 5 eV

 - Scintillation: appr. 20 eV

 - Phonons: meV

 - Breakup of Cooper pairs: meV

Ionization chambers can be made with any medium that allows charge collection to a pair of electrodes

The medium can be: Gas, Liquid, **Solid**

	gas	liquid	solid
density	low	moderate	high
atomic number Z	low	moderate	moderate
ionization energy ϵ_i	moderate	moderate	low
signal speed	moderate	moderate	fast

Desirable properties:

Low ionization energy \longrightarrow Increased charge yield dq/dE

Superior resolution

$$\frac{\Delta E}{E} \sim \frac{1}{\sqrt{N}} \sim \frac{1}{\sqrt{E/\epsilon_i}} \sim \sqrt{\epsilon_i}$$

High field in detection volume \longrightarrow Fast response

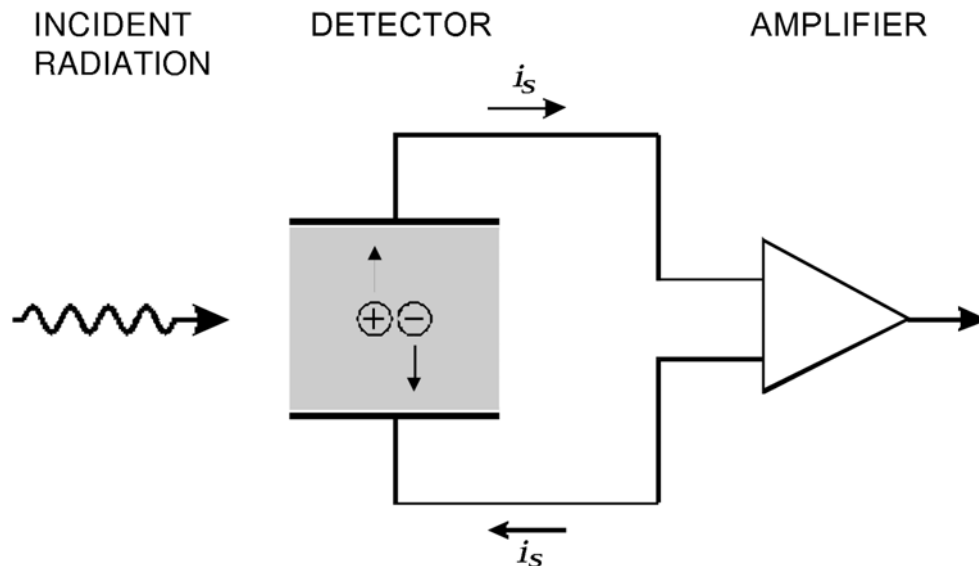
Improved charge collection efficiency

Q: what is the simplest solid-state detector ?

A: **Photoconductor**: Change of resistivity upon irradiation

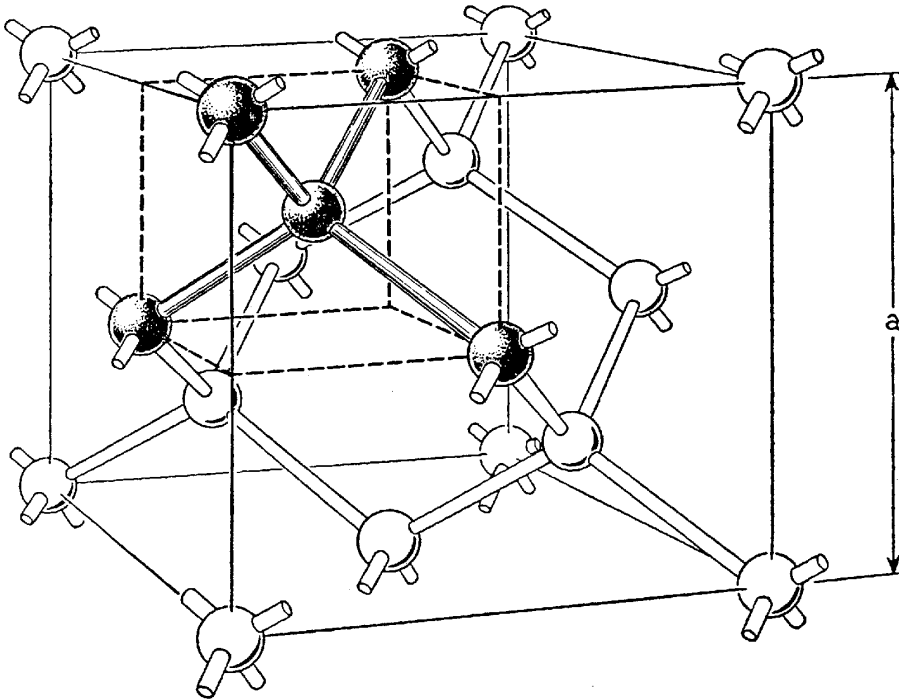


Semiconductor detectors are ionization chambers:



Semiconductor crystals

Lattice structure of diamond, Si, Ge (Diamond structure)



The crystalline structure leads to formation of electronic bandgaps

a = Lattice constant

Diamond:

$a = 0.356 \text{ nm}$

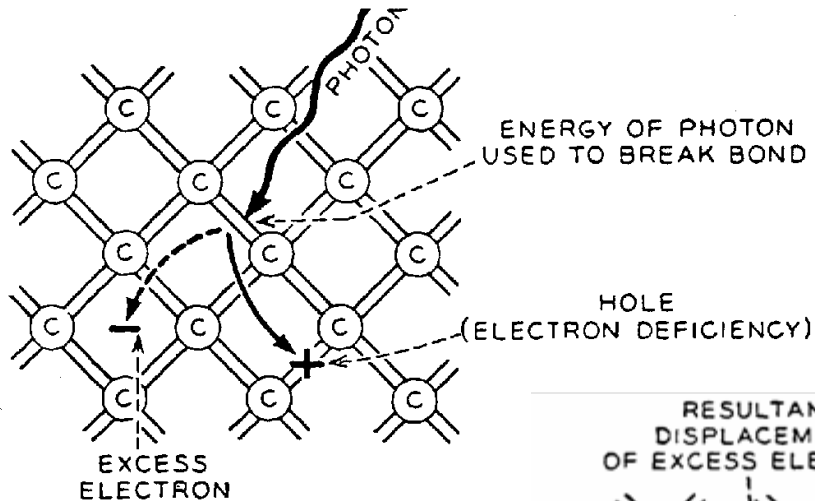
Ge:

$a = 0.565 \text{ nm}$

Si:

$a = 0.543 \text{ nm}$

Creation of electron-hole pairs



(a) PRODUCTION OF A HOLE-ELECTRON PAIR BY A PHOTON

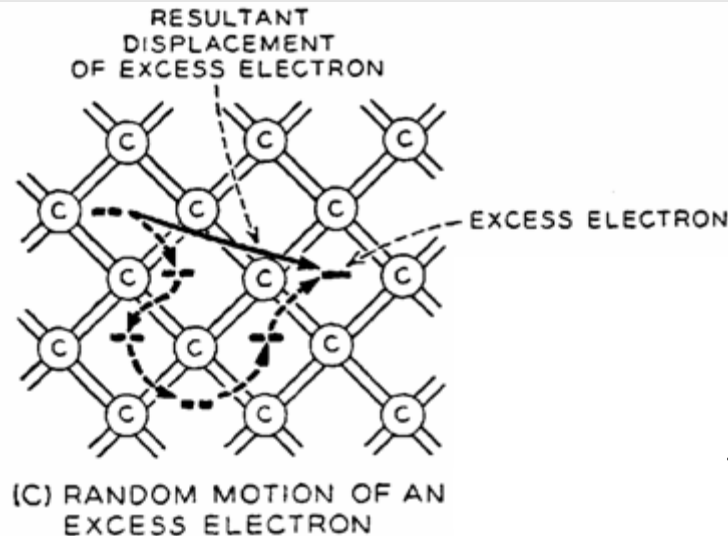
The electron can move freely

The hole is filled by a nearby electron, thus moving to another position

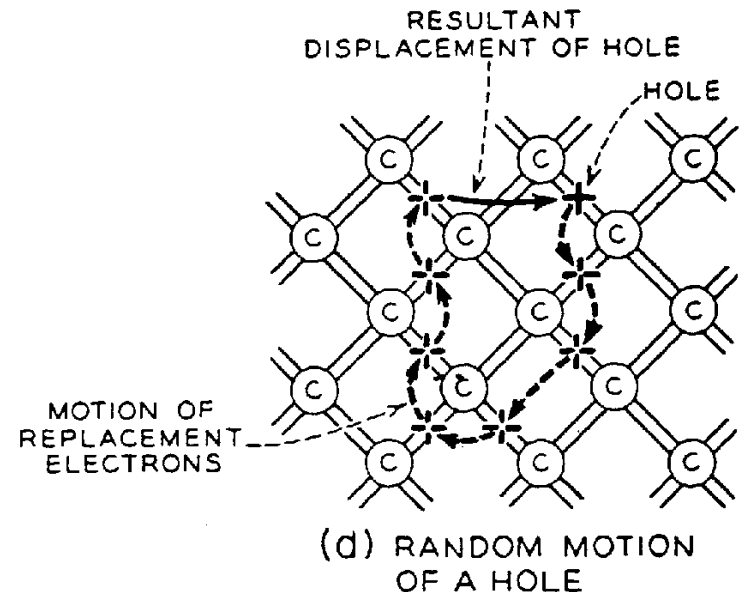
Holes behave like positive charge carriers. They move more slowly because hole transport involves many particles

Upon absorption of a photon, a bond can be broken which

- excites an electron into the conduction band and
- leaves a vacant state in the valence band

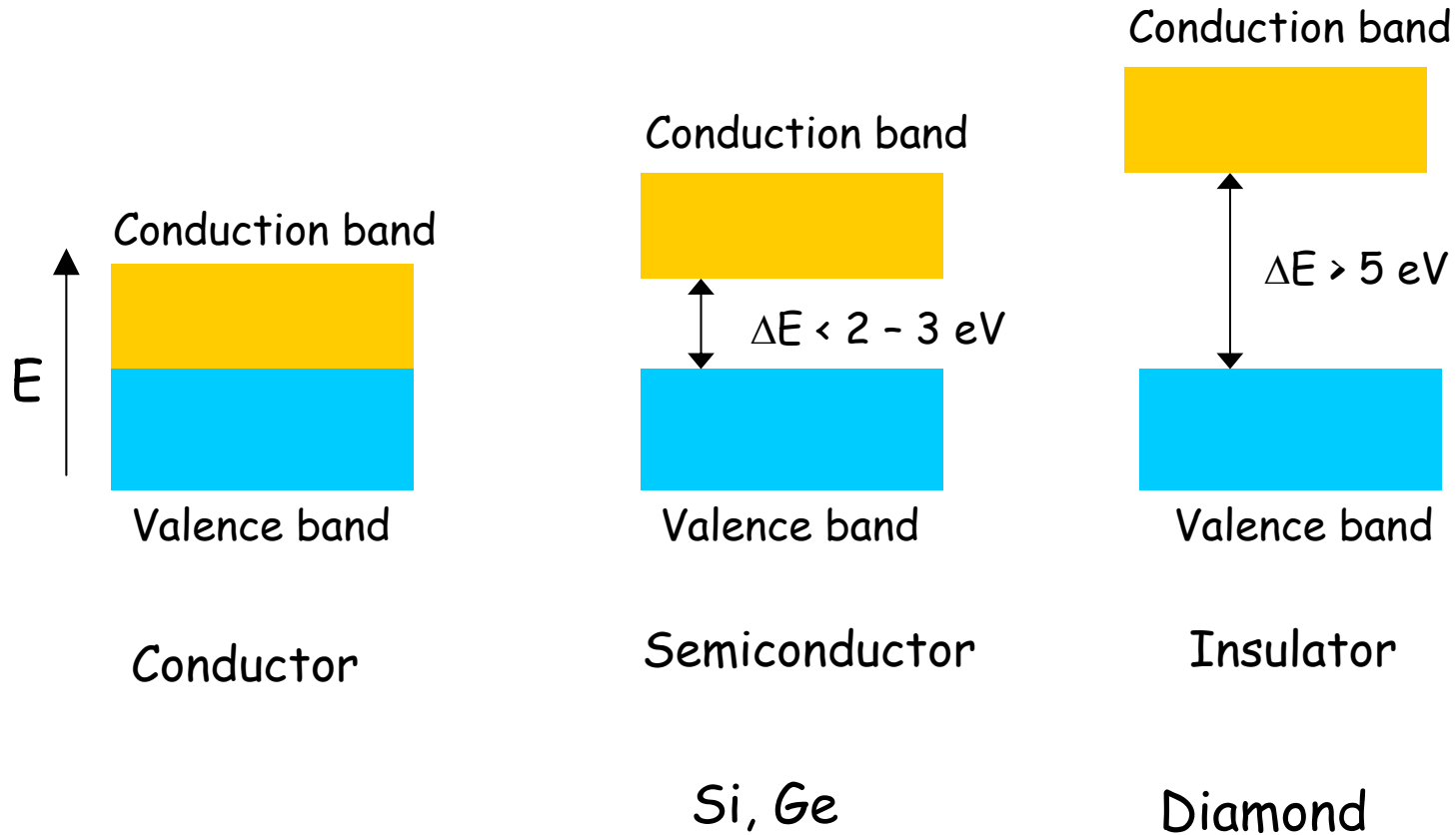


(c) RANDOM MOTION OF AN EXCESS ELECTRON

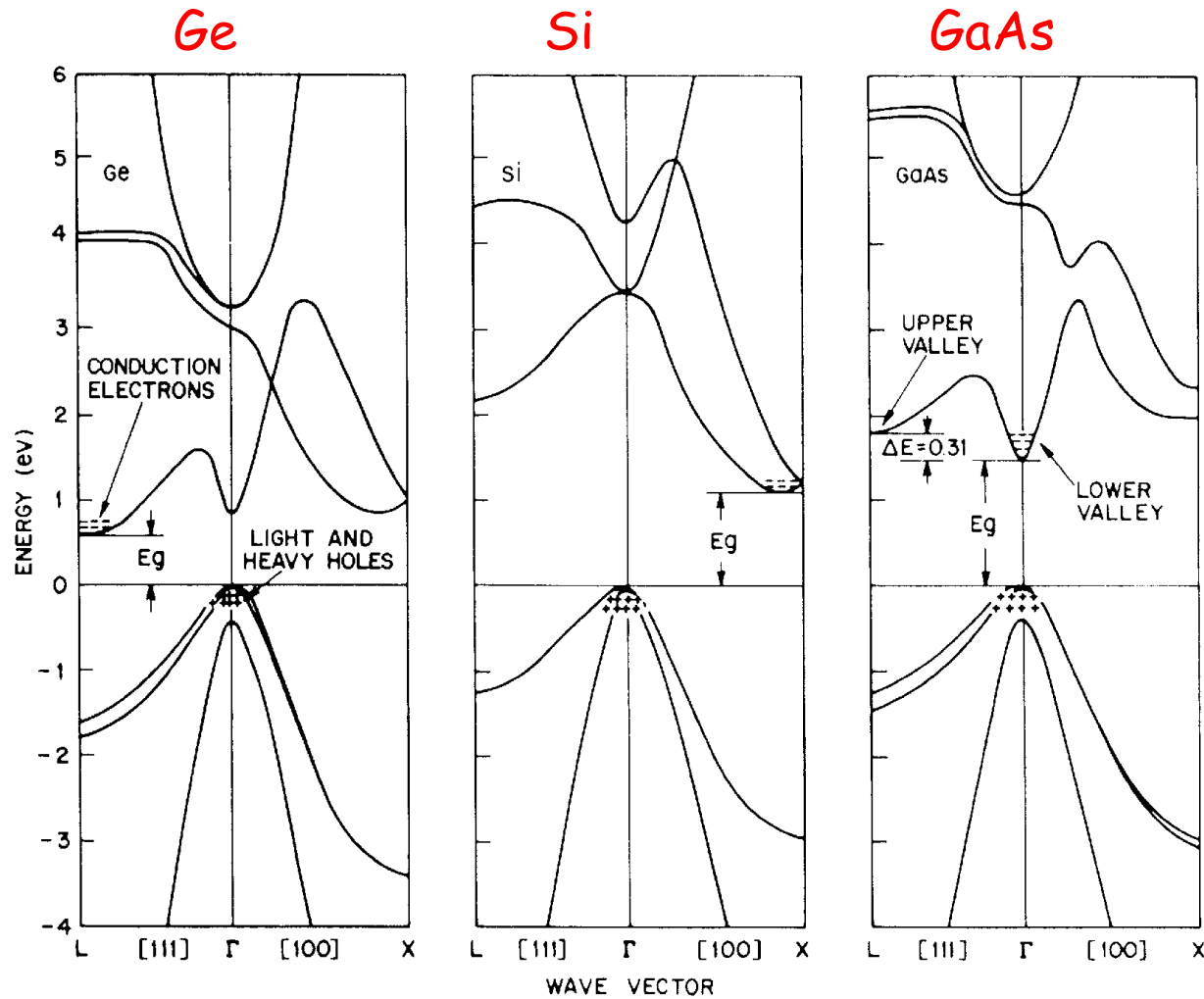


(d) RANDOM MOTION OF A HOLE

Classification of Conductivity



Band structure (3)



$$E_g = 0.7 \text{ eV}$$

$$E_g = 1.1 \text{ eV}$$

$$E_g = 1.4 \text{ eV}$$

Indirect band gap

Direct band gap

Properties of semiconductors

Property	Si	Ge	GaAs	Diamond
Atomic Number	14	32	31/33	6
Atomic Mass [amu]	28.1	72.6	144.6	12.6
Band Gap [eV]	1.12	0.66	1.42	5.5
Radiation Length X_0 [cm]	9.4	2.3	2.3	18.8
Average Energy for Creation of an Electron-Hole Pair [eV]	3.6	2.9	4.1	~ 13
Average Energy Loss dE/dx [MeV/cm]	3.9	7.5	7.7	3.8
Average Signal [$e^-/\mu\text{m}$]	110	260	173	~ 50
Intrinsic Charge Carrier Concentration [cm^{-3}]	$1.5 \cdot 10^{10}$	$2.4 \cdot 10^{13}$	$1.8 \cdot 10^6$	$< 10^3$
Electron Mobility [cm^2/Vs]	1500	3900	8500	1800
Hole Mobility [cm^2/Vs]	450	1900	400	1200

Si Currently best quality material

Ge Small band gap, i.e., high generated charge. Well suited for energy measurements

GaAs good ratio of generated charge/noise, charge collection efficiency dependent on purity and composition, radiation hard

Diamond radiation hard, expensive

Energy required for creation of an electron-hole pair

Ionization Energy > Band Gap

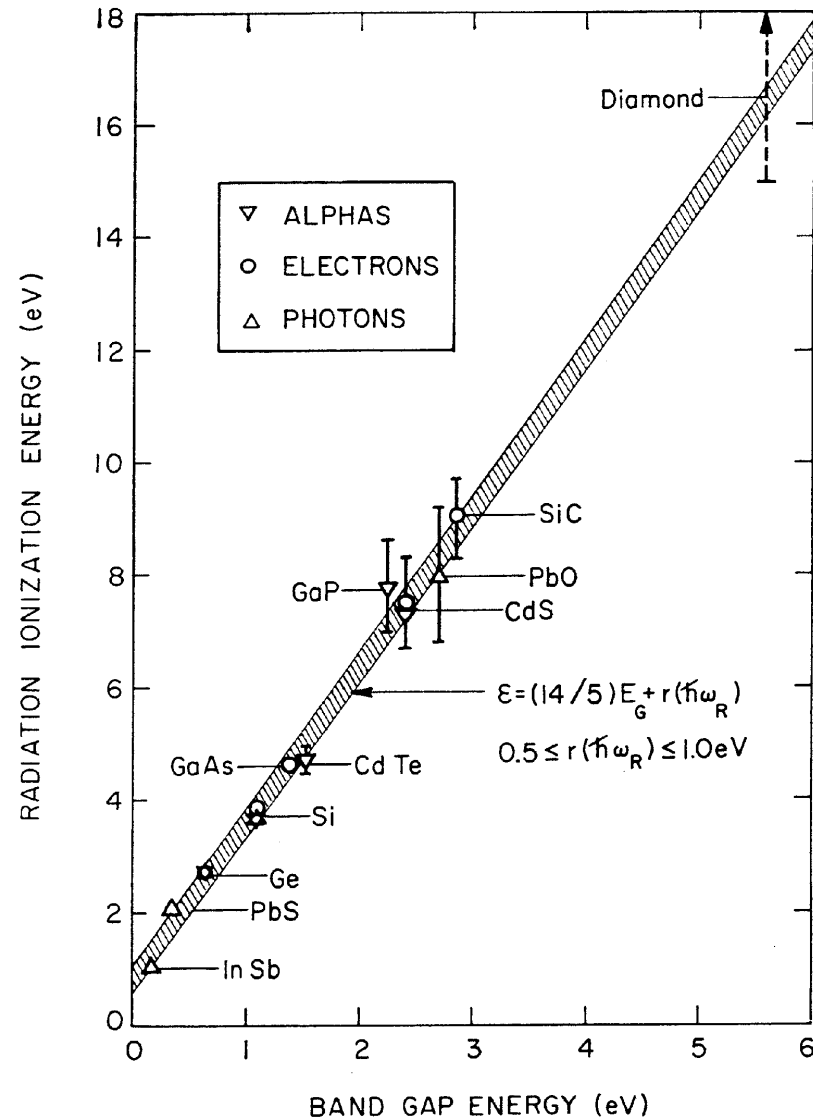
Formation of e-h pairs
requires both

- 1) Conservation of energy
- 2) Conservation of momentum

————→ additional energy
excites phonons

$$\varepsilon_i = C_1 + C_2 * E_g$$

Independent of material
and type of radiation



Silicon as detector material

Energy gap : $E_g = 1.12 \text{ eV}$

Ionization energy : $\epsilon_i = 3.6 \text{ eV}$

Density : $\rho = 2.33 \text{ g/cm}^3$

Example: Estimation of generated charge

Thickness : $d = 300 \text{ }\mu\text{m}$

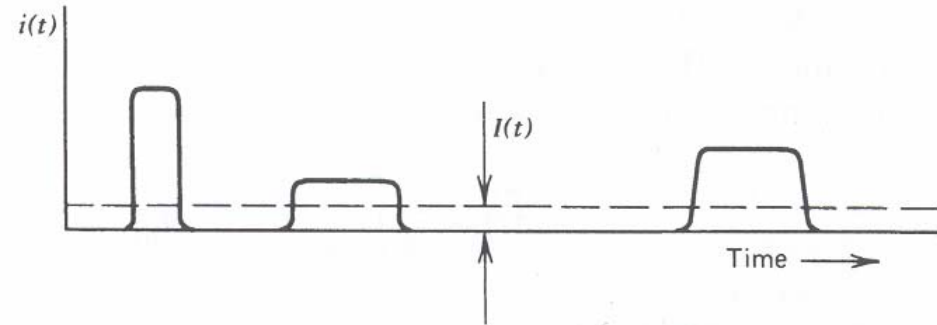
$$dE/dx|_{\min} = 1.664 \text{ MeV/g cm}^{-2}$$

$$\longrightarrow N = \rho d \frac{dE}{dx} \frac{1}{\epsilon_i} = 32000$$

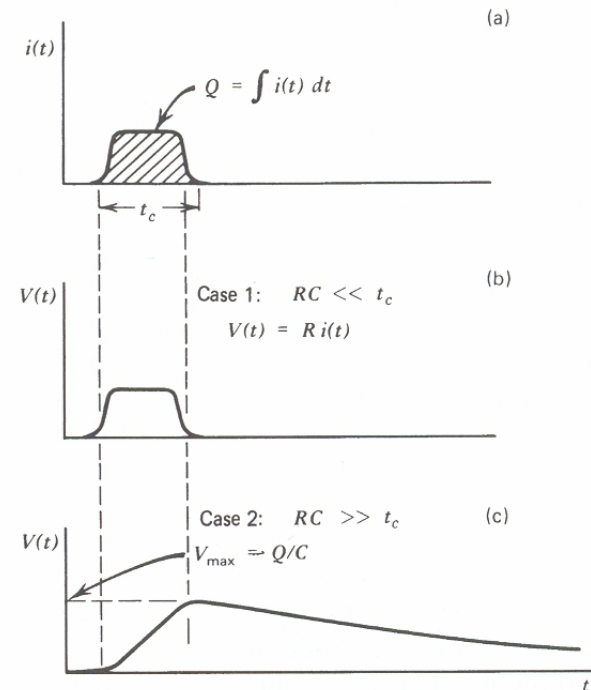
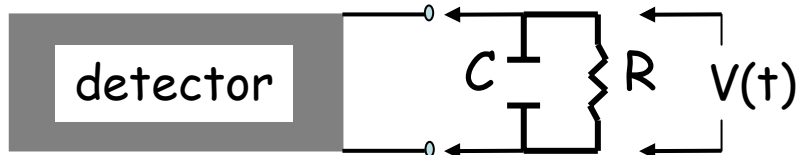
- This is a very strong signal and easy to measure
- High charge mobility, fast collection, Δt appr. 10 ns
- Good mechanical stability

How can we measure this ?

1) Current mode measurement:



2) Pulse mode measurement:



Intermezzo:
what is the “Fano-Factor” ?

Fluctuations in the Signal Charge: The Fano Factor

Observation : Many radiation detectors show an inherent fluctuation in the signal charge that is less than predicted by Poisson statistics

Fano factor :
$$F = \frac{\text{Observed variance in } N}{\text{Poisson predicted variance}}$$

The mean ionization energy exceeds the bandgap because conservation of momentum requires excitation of phonons

Upon deposition of energy E_0 , two types of excitations are possible:

- a) Lattice excitation with no formation of mobile charge
→ N_x excitations produce N_p phonons of energy E_x
- b) Ionization with formation of a mobile charge pair
→ N_i ionizations form N_Q charge pairs of energy E_i

In other words:
$$E_0 = E_i N_i + E_x N_x$$

The total differential :
$$dE_0 = \frac{\partial E_0}{\partial N_x} dN_x + \frac{\partial E_0}{\partial N_i} dN_i = 0$$

Thus : $E_x \Delta N_x + E_i \Delta N_i = 0$

This means : If for a given event more energy goes into charge formation, less energy will be available for excitation

From averaging over many events one obtains for the variances :

$$E_i \sigma_i = E_x \sigma_x$$

With $\sigma_x = \sqrt{N_x}$ (assuming Gaussian statistics)

It follows: $\sigma_i = \frac{E_x}{E_i} \sqrt{N_x}$

From the total energy

$$E_i N_i + E_x N_x = E_0$$

It follows:

$$N_x = \frac{E_0 - E_i N_i}{E_x}$$

$$\sigma_i = \frac{E_x}{E_i} \sqrt{\frac{E_0}{E_x} - \frac{E_i}{E_x} N_i}$$

Each ionization leads to a charge pair that contributes to the signal. Therefore:

$$N_i = N_Q = \frac{E_0}{\epsilon_i}$$

and:
$$\sigma_i = \frac{E_x}{E_i} \sqrt{\frac{E_0}{E_x} - \frac{E_i}{E_x} \frac{E_0}{\epsilon_i}} = \sqrt{\frac{E_0}{\epsilon_i}} \cdot \sqrt{\frac{E_x}{E_i} \left(\frac{\epsilon_i}{E_i} - 1 \right)}$$

Fano factor F

Thus, the variance in signal charge Q is given by :

$$\sigma_Q = \sqrt{FN_Q}$$

For silicon :

$E_x = 0.037 \text{ eV}$	$\longrightarrow F = 0.08 \quad (\text{exp. Value: } F = 0.1)$ \downarrow $\sigma_Q \approx 0.3 \sqrt{N_Q}$
$E_i = E_g = 1.1 \text{ eV}$	
$\epsilon_i = 3.6 \text{ eV}$	

This means, the variance of the signal charge is smaller than naively expected.

Ref.: U. Fano, Phys. Rev. 72, 26 (1947)

Bottom line:

Only if all generated electron-hole pairs were independent:

$$\sigma_Q = \sqrt{N_Q}$$

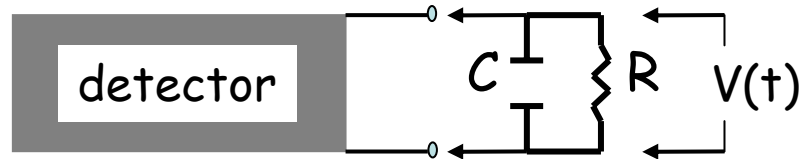
But they all originate from the same event
→ cannot be independent → variance smaller
this is material dependent!

$$\sigma_Q = \sqrt{F \times N_Q}$$

With F smaller than 1.

End Intermezzo:
what is the “Fano-Factor” ?

Q: If a detector is this simple:



why do we need so many expensive people ?

A: Because this photoconductor detector does not do the job!

Q: Why not?

A: Thermally generated dark current \gg signal current !

Charge Carrier Density

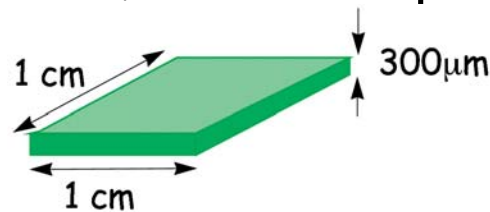
Thermally activated charge carriers in the conduction band

Their density is given by

$$n_i = \sqrt{n_V n_C} \exp\left(-\frac{E_G}{2k_B T}\right) = 1.5 \times 10^{10} \text{ cm}^{-3}$$

at room temperature

In a typical Si detector volume one obtains 4.5×10^8 free carriers compared to 3.2×10^4 e-h pairs for MIP



For a detection of such an event, the number of free carriers has to be substantially reduced.

This can be achieved via

a) cooling

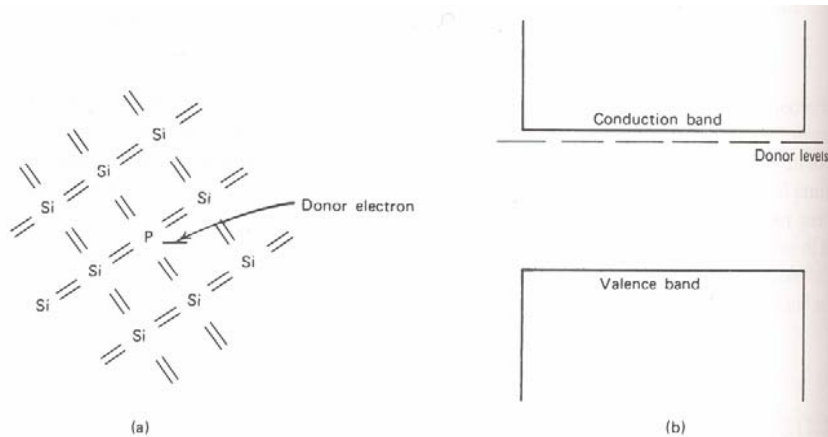
b) **pn-junction in reverse bias**

Doping of semiconductors

By addition of impurities (doping) the conductivity of semiconductors can be tailored:

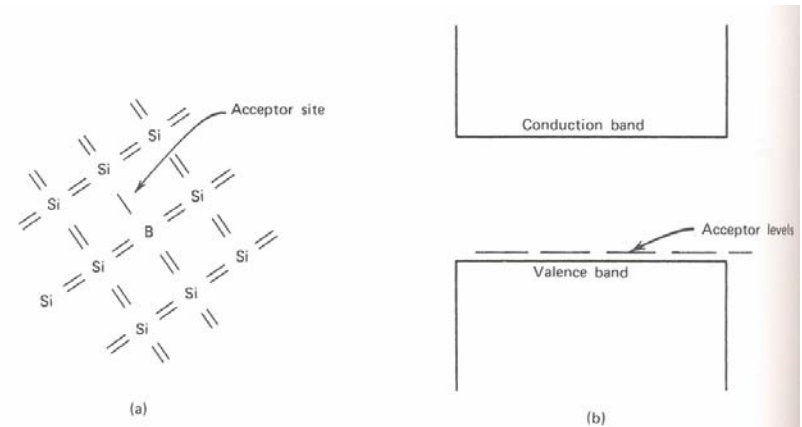
By doping with elements from group V (Donor, e.g., As, P) one obtains **n-type** semiconductors

One valence electron without partner, i.e. impurity contributes excess electron



By doping with elements from group III (Acceptor, e.g., B) one obtains **p-type** semiconductors

One Si valence electron without a partner, impurity borrows an electron from the lattice



Use for:

Detectors

Electronics

Doping concentration

$10^{12} - 10^{15} \text{ cm}^{-3}$

$10^{17} - 10^{18} \text{ cm}^{-3}$

Resistivity

$\sim 5 \text{ k}\Omega \text{ cm}$

$\sim 1 \Omega \text{ cm}$

In a n-type semiconductor (Si):

- Due to doping: $N_d = 10^{15}$ electrons and 0 holes
- Due to thermal generation: $n_i = 10^{10}$ electrons and $p_i = 10^{10}$ holes

→ N_d so large that it will compensate many holes so that: $np = n_i p_i$

$$np = N_d p = 10^{15} p = n_i p_i = 10^{20} \rightarrow p = 10^5.$$

Means mainly one type of carrier = electrons = Majority carriers
Holes are minority carriers. Opposite situation for p-type silicon

Note: $n+p = 10^{15}$ instead of 2×10^{10} → much more conducting!

Resistivity ρ can be calculated by:

$$\rho = \frac{1}{e N_D \mu_e}$$

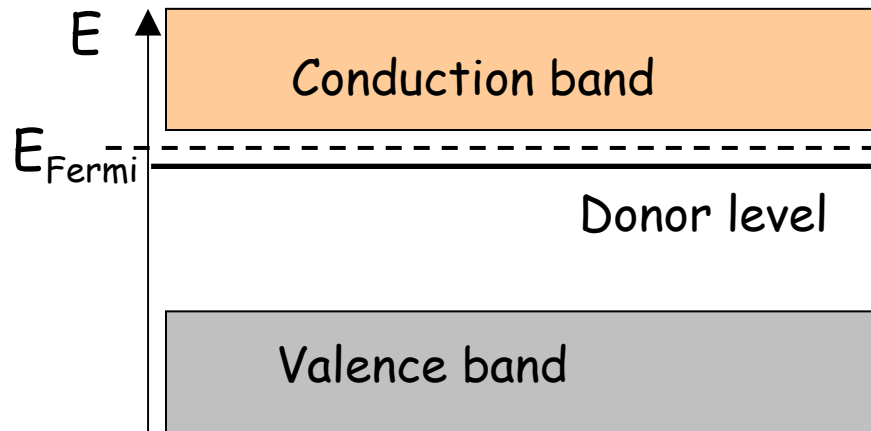
Similar expression for
p-type silicon

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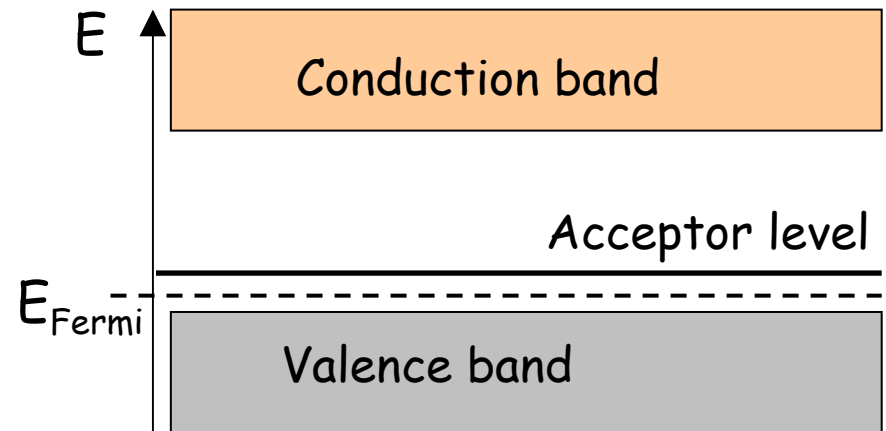
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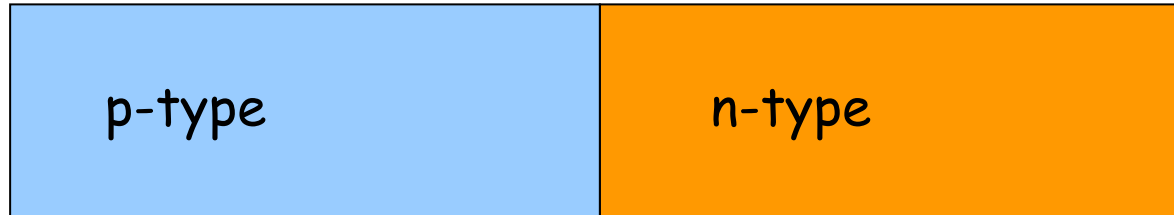
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The p-n junction (1)

Donor region and acceptor region adjoin each other :



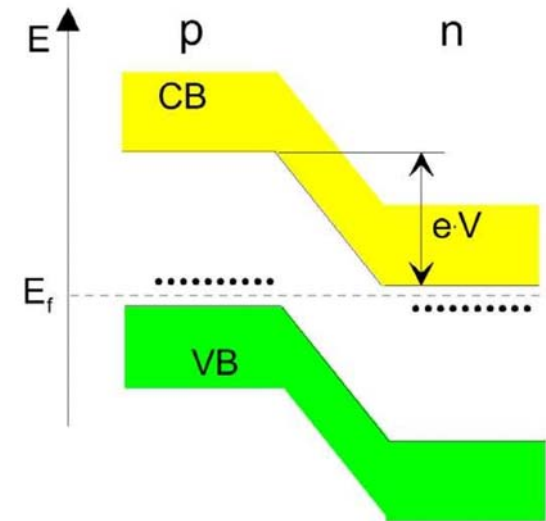
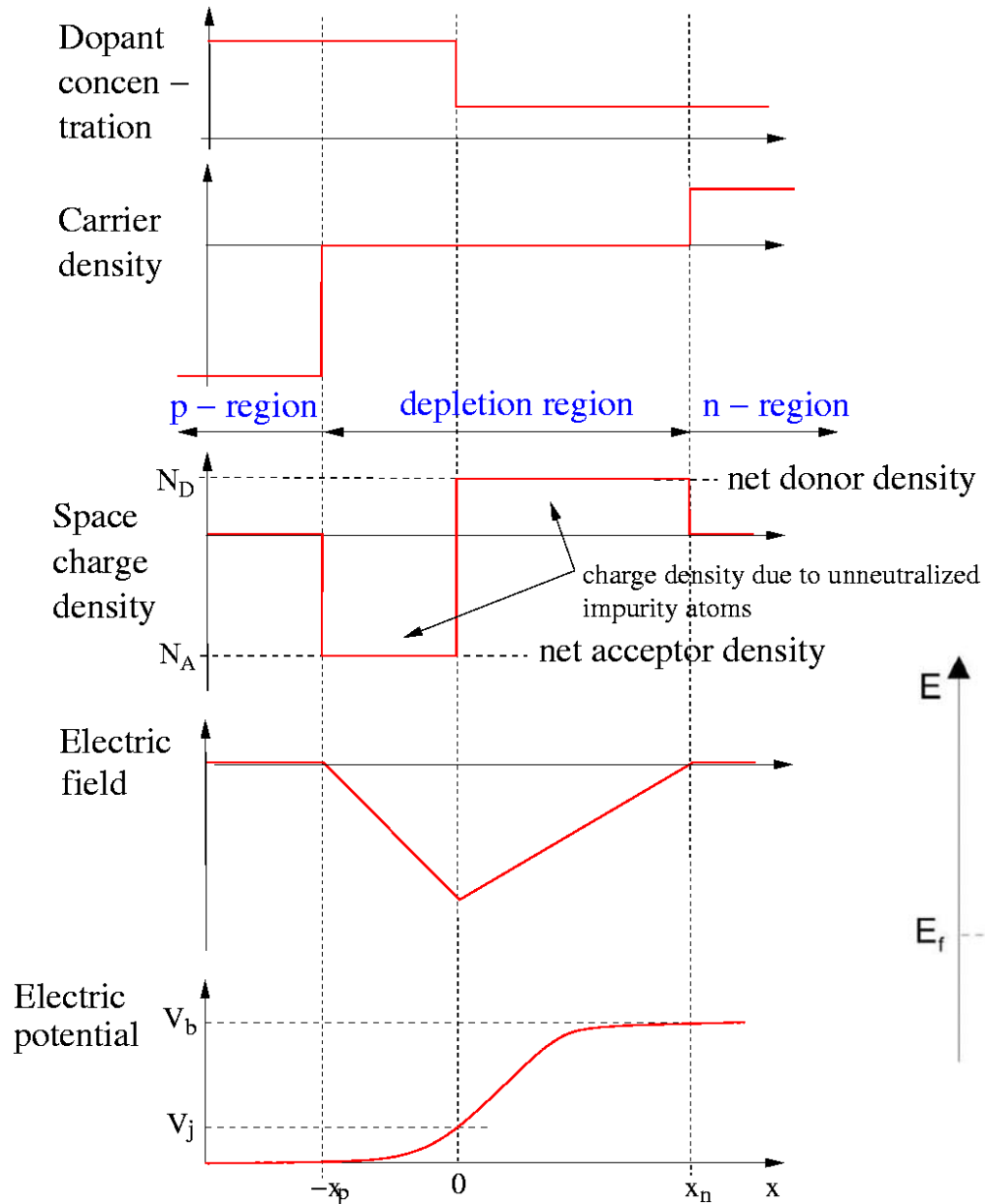
Thermal diffusion drives holes and electrons across the junction

Electrons diffuse from the n- to the p-region, leaving a net positive **space charge** in the n-region and building up a **potential** (similar process for the holes)

The diffusion depth is limited when the space charge potential energy exceeds the energy for thermal diffusion

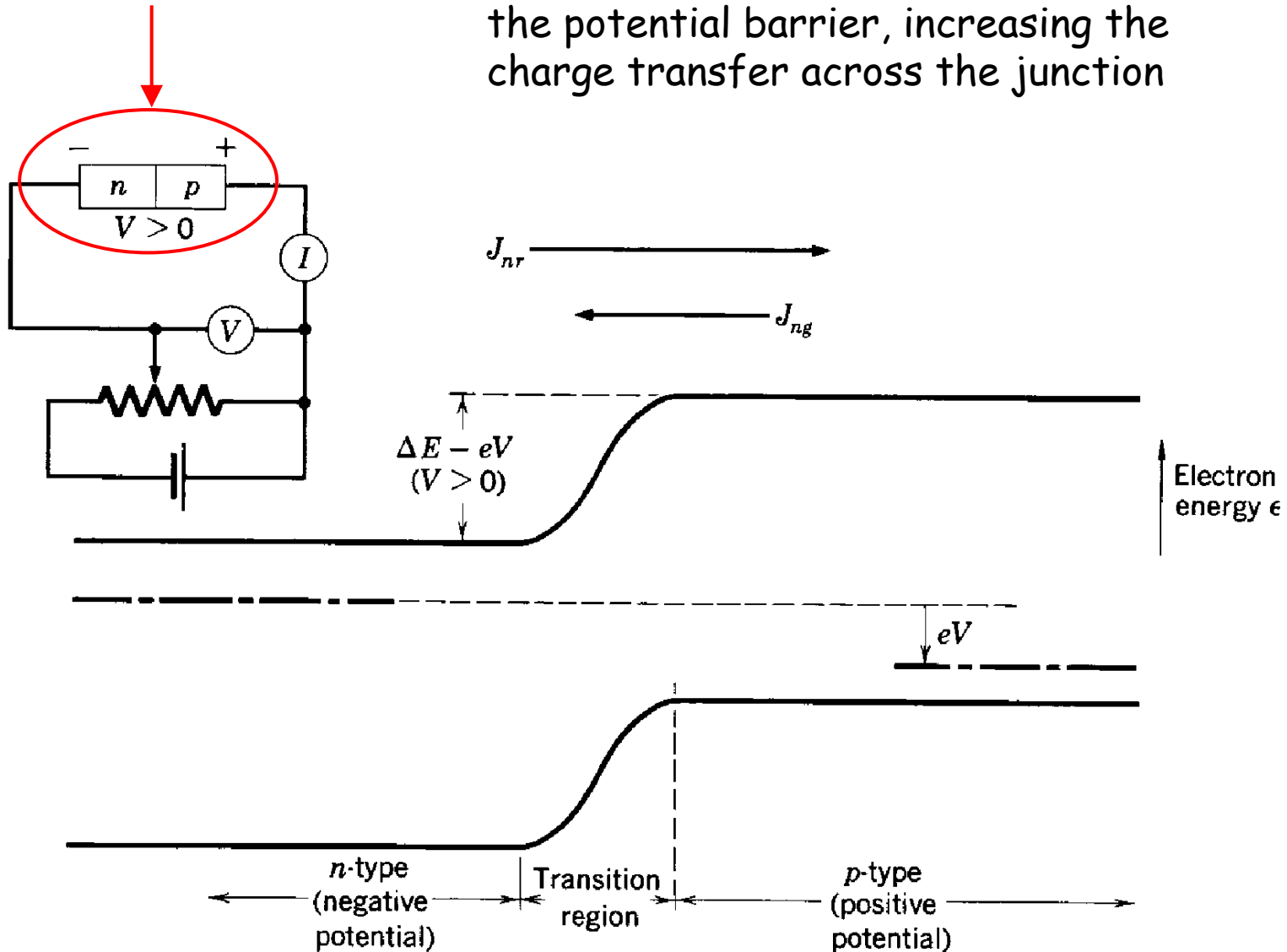
Due to preparation conditions (implantation), the p-n junction is often **highly asymmetric**

The p-n junction (2)



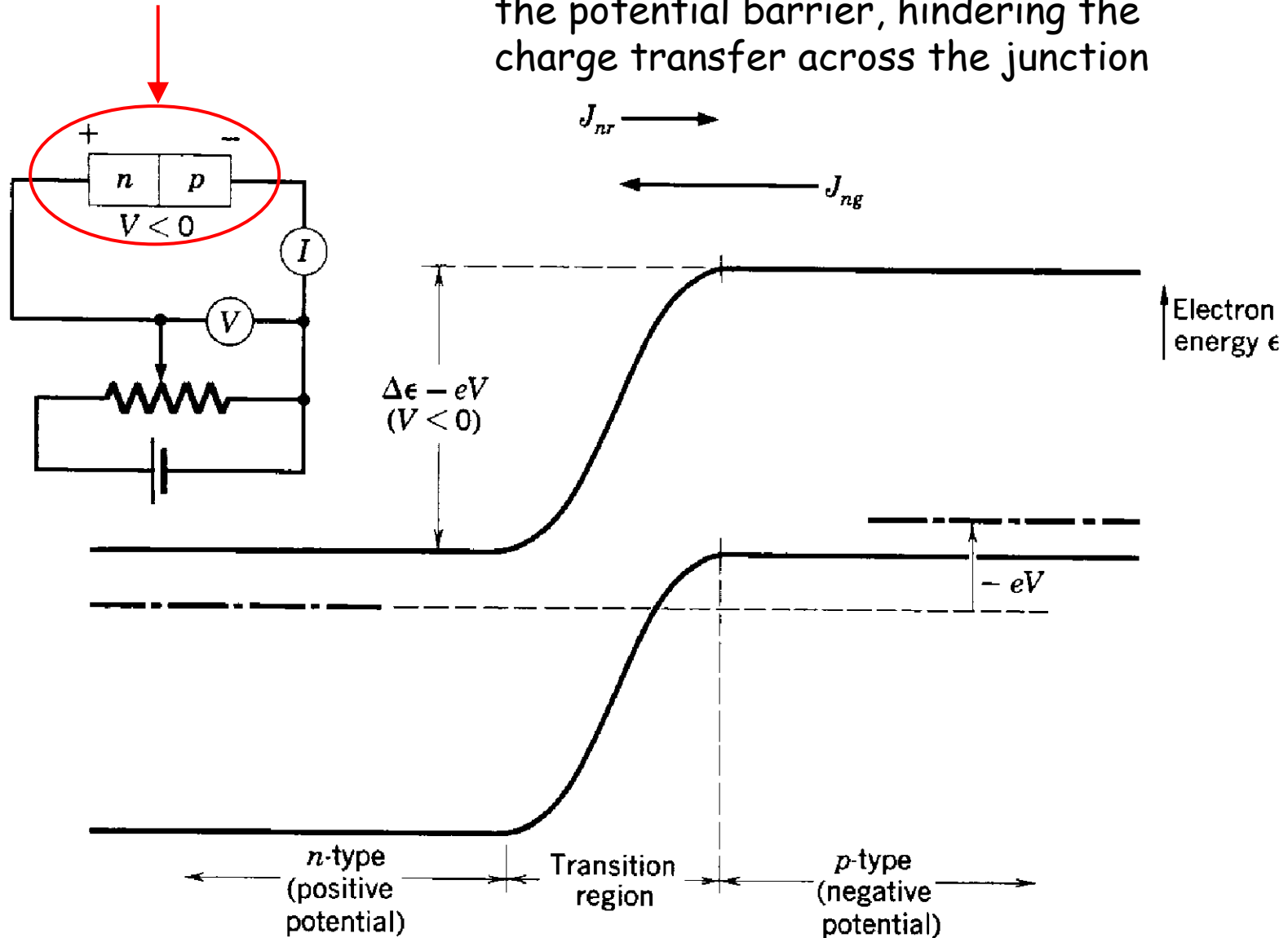
Forward bias

The externally applied voltage reduces the potential barrier, increasing the charge transfer across the junction

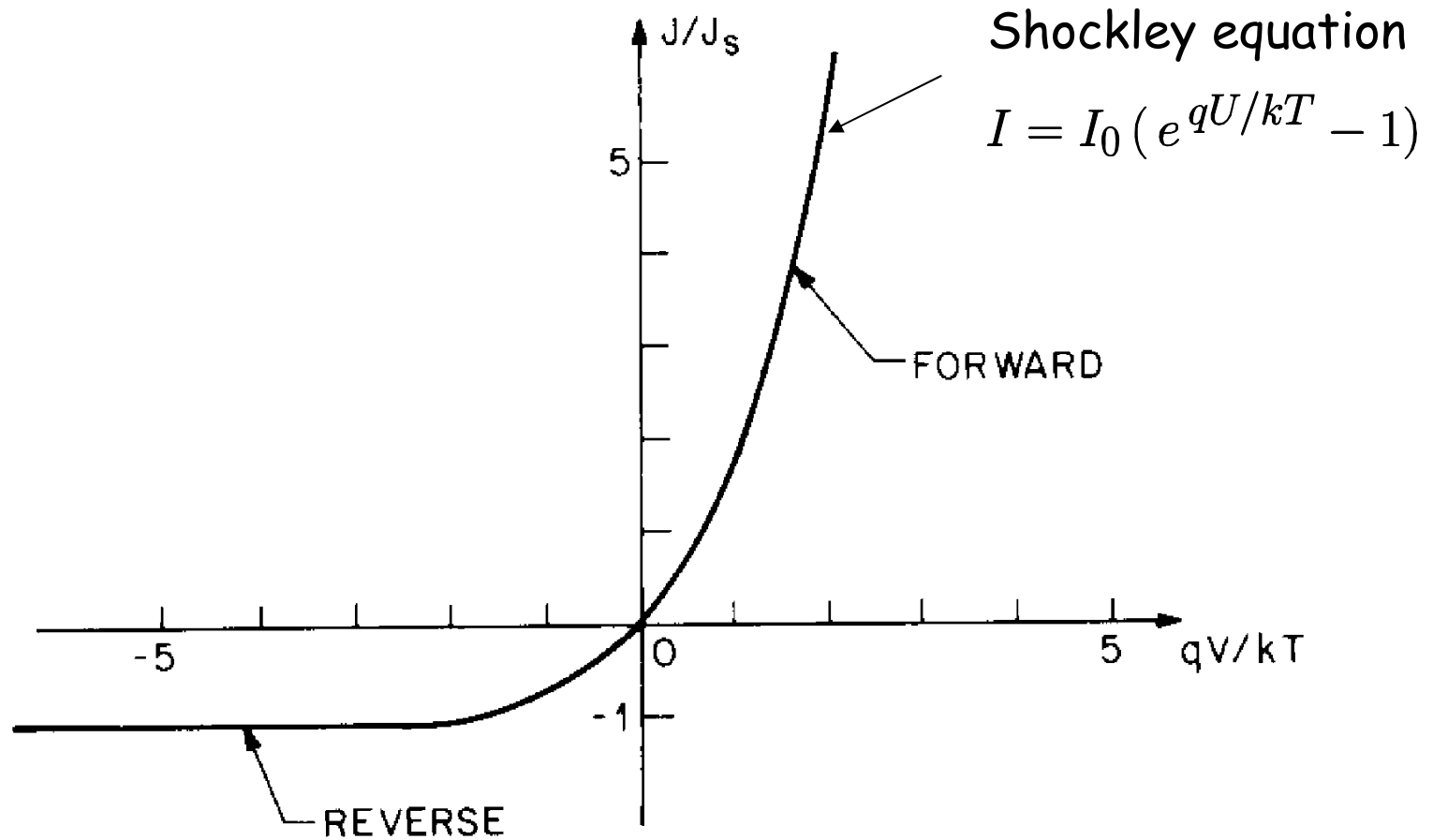


Reverse bias

The externally applied voltage increases the potential barrier, hindering the charge transfer across the junction



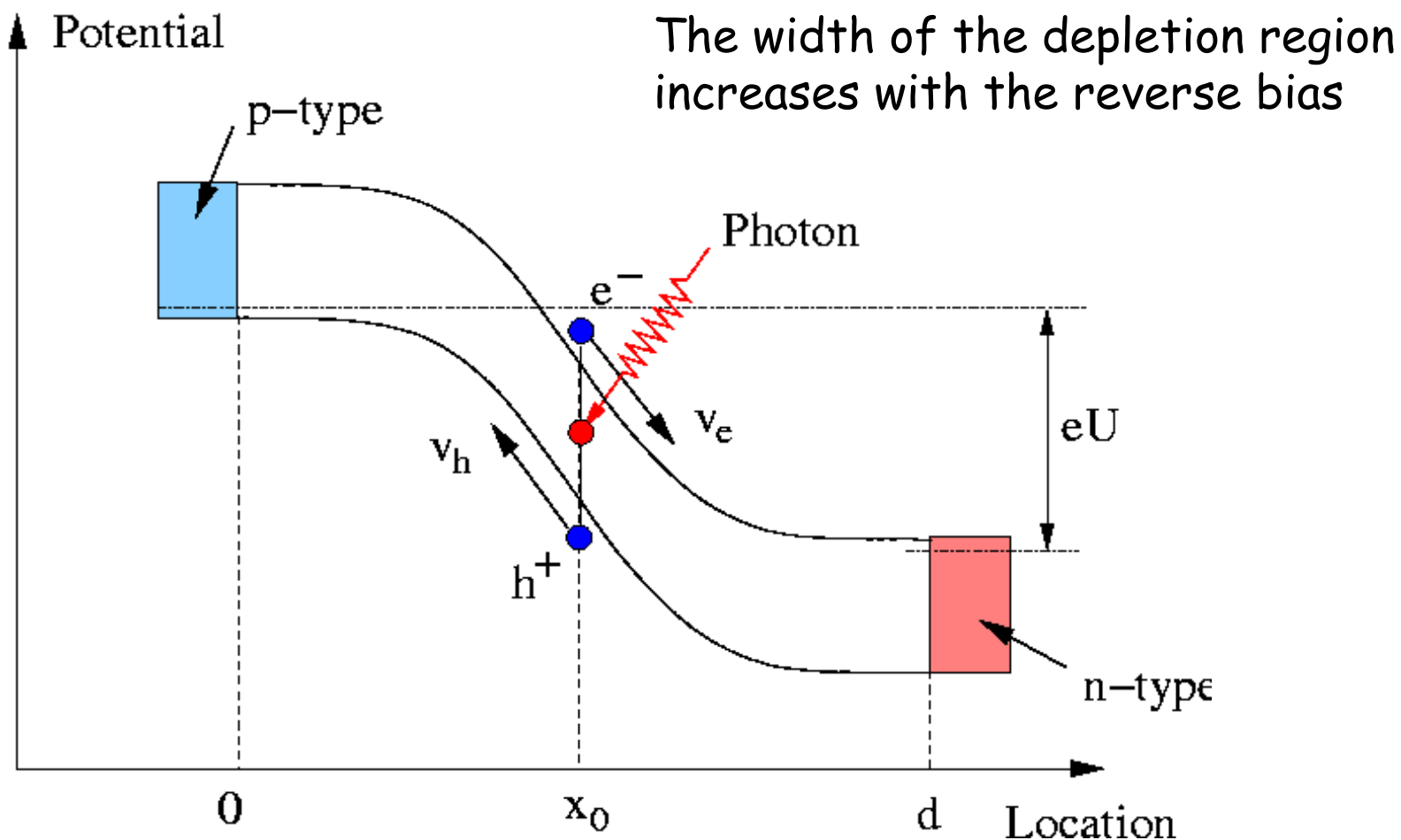
Diode current vs. voltage



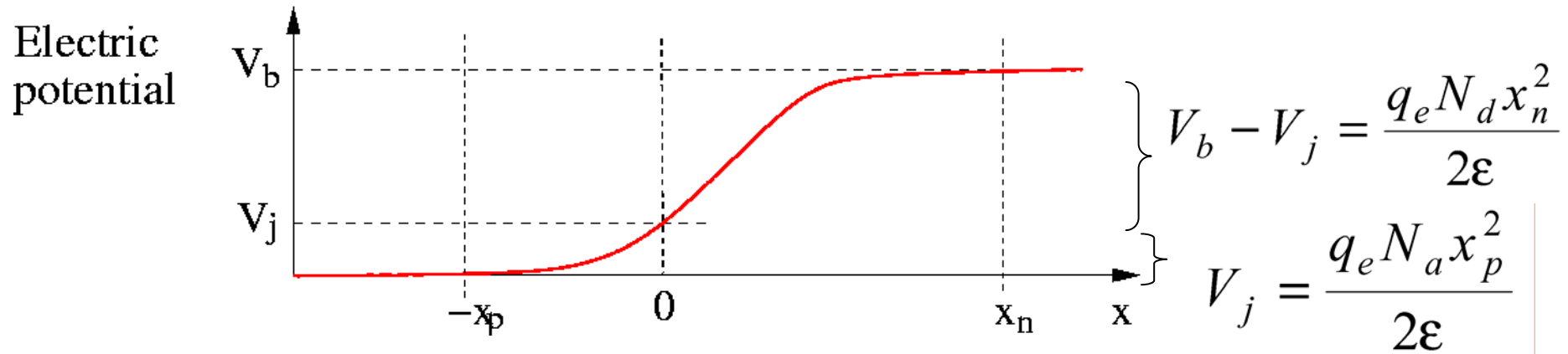
from Sze, Physics of Semiconductor Devices

p-n junction with reverse bias

Since the depletion region is a volume with an electric field, it can be used as a radiation detector:



The pn - junction: Properties in reverse bias



What determines the shape of this curve, i.e., what is

- 1) The magnitude of the potential V_b ?
- 2) The width of the depletion zone $W = x_p + x_n$?

$$\frac{d^2 V}{dx^2} + \frac{N q_e}{\epsilon} = 0 \quad \text{Poisson's equation;}$$

with ϵ the relative permittivity

Two successive integrations: Electric field and potential

$$\frac{dV}{dx} = -\frac{q_e N_d}{\epsilon} (x - x_n) \quad \left| \quad V = -\frac{q_e N_d}{\epsilon} \left(\frac{1}{2} x^2 - x x_n \right) + V_j \right.$$

Depletion width of the p-n junction in reverse bias

Bias voltage :
$$V_b = \frac{q_e}{2\epsilon} (N_d x_n^2 + N_a x_p^2)$$

Charge neutrality :
$$N_d x_n = N_a x_p$$

Both equations can be solved for x_p and x_n resulting in the following expression for the depletion width :

$$W = x_n + x_p = \sqrt{\frac{2\epsilon V_b}{q_e} \frac{N_a + N_d}{N_a N_d}}$$

If, for example, $N_a \gg N_d$, this expression simplifies to

$$W \approx x_n = \sqrt{\frac{2\epsilon V_b}{q_e N_d}}$$